

CLAIMS

1. A method for forming by molding a plastic protective package for an electronic integrated circuit comprising an electronic device activated from the outside of said protective package, the method comprising the following steps:

dispensing a covering layer of elastic material on a portion of said electronic device;
shaping said covering layer to form a projecting portion from a surface of said electronic device;

molding said electronic integrated circuit in said plastic protective package using a mold including at least a half-mold abutting against said projecting portion;

obtaining a hole or a window formed in alignment with said projecting portion in said protective package.

2. The method according to claim 1 wherein said covering layer is formed by elastic material.

3. The method according to claim 2 wherein said projecting portion is realized by volumetric dispensing of said elastic material.

4. The method according to claim 2 wherein said elastic material is a silicon gel.

5. The method according to claim 2 wherein said projecting portion is realized by screen printing of said elastic material.

6. The method according to claim 5 wherein said elastic material is a silicon gel.

7. The method according to claim 1 wherein said projecting portion is shaped as a ring.

8. The method according to claim 1, comprising a further step of forming a dyke or barrier on the electronic device to surround said projecting portion.

9. The method according to claim 8 wherein said dyke or barrier is formed before said covering layer on the electronic device.

10. The method according to claim 1 wherein that said half-mold has a lug protruding inside the mold and abutting against said projecting portion during the molding step.

11. The method according to claim 1 wherein that said covering layer is removed after the molding step.

12. A mold for molding a plastic protective package encapsulating an integrated electronic circuit that includes an electronic device, the mold comprising a pair of superimposed half-molds defining a mold cavity for containing said integrated circuit, wherein one half-mold has a lug protruding substantially at a location of said electronic device and abutting against the electronic device during a molding step.

13. The mold for molding a plastic protective package according to claim 12 wherein a covering layer is interposed between said lug and said electronic device during the molding step.

14. The mold for molding a plastic protective package according to claim 13 wherein said covering layer is shaped to form a projecting portion from said electronic device.

15. The mold for molding a plastic protective package according to claim 12 wherein said projecting portion is shaped to form a ring.

16. The mold for molding a plastic protective package according to claim 13 wherein said covering layer covers the integrated device.

17. The mold for molding a plastic protective package according to claim 12 wherein said lug is cylindrical in shape.

18. The mold for molding a plastic protective package according to claim 12 wherein said lug is truncated conical in shape.

19. A plastic protective package for a semiconductor-integrated electronic circuit, comprising a support for an electronic device that can be at least partially activated from the outside of said protective package; wherein said protective package is provided with a hole or a window aligned to at least one portion of said integrated device that is at least partially filled by a projecting portion of elastic material projecting from a surface of the electronic device.

20. The plastic protective package according to claim 19 wherein said projecting portion is shaped to form a ring on the integrate device.

21. The plastic protective package according to claim 19 wherein said hole has tapering walls toward said electronic circuit.

22. The plastic protective package according to claim 19 wherein said projecting portion is surrounded by dyke or barrier formed on the surface of the electronic device.

23. The plastic protective package according to claim 19 wherein said projecting portion is surrounded by dyke or barrier formed around the electronic device.